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RECORDATION FORM COVER SHEET

To the Director of the U.S. Patent and Trademark Office:
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22387 U.S. PTO
10/757421
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<p>1. Name of conveying party(ies): [FAMILY NAME (ALL CAPS), Given Name] HSU, Cheng-Chung</p> <p>, , , ,</p> <p>Additional name(s) of conveying party(ies) attached? <input type="checkbox"/> YES <input checked="" type="checkbox"/> NO</p>	<p>2. Name and address of receiving party(ies) Name: INVENTEC CORPORATION Internal Address: Street Address: Inventec Bldg., 66 Hou-Kang St., Shih-Lin District City: Taipei State: ZIP: Country: Taiwan, R.O.C. Postal Code:</p> <p>Additional name(s) & address(es) attached? <input type="checkbox"/> YES <input checked="" type="checkbox"/> NO</p>
<p>3. Nature of conveyance:</p> <p><input checked="" type="checkbox"/> Assignment <input type="checkbox"/> Merger <input type="checkbox"/> Security Agreement <input type="checkbox"/> Change of Name <input type="checkbox"/> Other:</p> <p>Execution Date: December 10, 2003</p>	<p>1-15-04</p> <p>10/757421</p>
<p>4. Application number(s) or patent number(s): If this document is being filed together with a new application, the execution date of the application is: December 10, 2003</p> <p>A. Patent Application No(s). NEW B. Patent No(s).</p> <p>Additional numbers attached? <input type="checkbox"/> YES <input checked="" type="checkbox"/> NO</p>	
<p>5. Name and address of party to whom correspondence concerning document should be mailed: Name: BIRCH, STEWART, KOLASCH & BIRCH, LLP Street Address: P.O. BOX 747 City: FALLS CHURCH State: VA ZIP: 22040-0747 Country: USA</p>	<p>6. Total No. of applications/patents involved: One (1)</p> <p>7. Total fee (37 C.F.R. § 3.41): \$40.00 <input checked="" type="checkbox"/> Enclosed <input checked="" type="checkbox"/> Authorized to be charged to deposit account, if no fee attached.</p> <p>8. Deposit account number: 02-2448</p> <p>(Attach triplicate copy of this page if paying by deposit account)</p>
<p>DO NOT USE THIS SPACE</p>	
<p>9. Statement and signature.</p> <p><u>Chao-Ming Chen</u> <u>Chen</u> <u>January 15, 2004</u> Limited Recognition Under 37 C.F.R. § 10.9(b) Signature Date</p>	
<p>Total number of pages including cover sheet, attachments, and document: Two (2)</p>	

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22601-1(030326)

ASSIGNMENT OF U.S. PATENT APPLICATION

In consideration of the sum of One Dollar in hand paid, and other good and valuable consideration, the receipt of which is hereby acknowledged, the undersigned

Inventor(s) (1) Cheng-Chung HSU
Full Name(s) _____

Hereby sell, assign and transfer to

Assignee INVENTEC CORPORATION
Name and Address Inventec Bldg., 66 Hou-Kang St., Shih-Lin District,
Taipei, Taiwan, R.O.C.

(hereinafter called the Assignee) the entire right, title, and interest in and to any and all improvements which are disclosed in the Application for United States Letters Patent entitled

Title of Invention: MODULARIZED ELECTRONIC DEVICE ASSEMBLY ARCHITECTURE

Which application was

Complete either a) executed by the undersigned on December 10, 2003
b) filed on the January 15, 2004
Serial No. NEW

Including any and all United States Letters Patents which may be granted therefore and any and all extensions, divisions, reissues, substitutes, renewals or continuations thereof, and the right to all benefits under the International Convention for the Protection of Industrial Property.

It is hereby authorized and requested that the Commissioner of Patents issue any and all of said Letters Patent, when granted, to said assignee.

Further, it is agreed that, when requested, without charge to but at the expense of said Assignee, the undersigned will execute all divisional, continuing, substitute, renewal, and reissue patent applications; execute all rightful other papers; and generally do everything possible which said Assignee shall consider desirable for aiding in securing and maintaining proper patent protection.

Date _____ Signed at Taiwan, R.O.C.
On December 10, 2003

Inventor(s) _____
Full Signature(s) Cheng Chung Hsu Cheng-Chung HSU

